

3.5x2.8mm PLCC4 SMD LED

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- RoHS compliant.

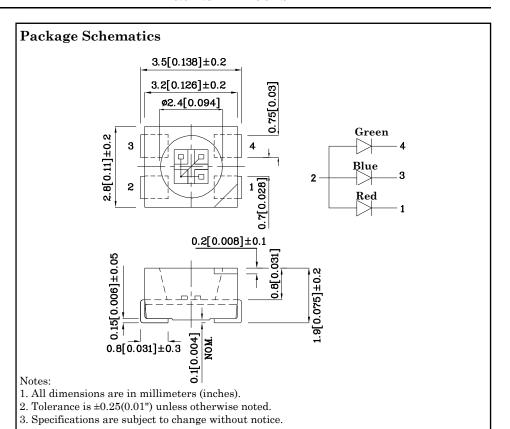






ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE



Red Blue Green Absolute Maximum Ratings (AlGa (InGa Unit (InGa (T_A=25°C) InP) N) N) V Reverse Voltage $V_{\rm R}$ 5 5 5 Forward Current $I_{\rm F}$ 30 30 30 mA Forward Current (Peak) 1/10 Duty Cycle i_{FS} 195 150 150 mA 0.1ms Pulse Width Power Dissipation P_{D} 75 120 123 mWElectrostatic Discharge Threshold 3000 250 V 450 (HBM) Operating Temperature $T_{\boldsymbol{A}}$ -40 ~ +85 ${}^{\circ}\mathrm{C}$ Storage Temperature Tstg

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Part

Operating Characteristics (T _A =25°C)		Red (AlGaIn P)	Blue (InGa N)	Green (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	3.3	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	4.0	4.1	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	50	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	630*	460*	515*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	621*	465*	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	20	25	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	25	100	45	pF

Luminous Intensity

Part Number	Emitting Color	Emitting Material	Lens-color	CIE127-2007* (I _F =20mA) mcd		CIE127-2007* nm λP	Angle 20 1/2
				min.	typ.		
	Red	AlGaInP		120*	218*	630*	
XZMECBDDG45S	Blue	InGaN	Water Clear	55*	98*	460*	120°
	Green	InGaN	_	400*	497*	515*	

Emitting

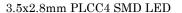
Emitting

XDSB7112 V5-Z Layout: Maggie L.

Wavelength

Viewing

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Sep 13 2016



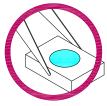


Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

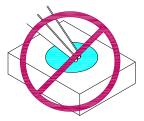
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

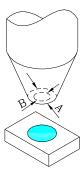




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



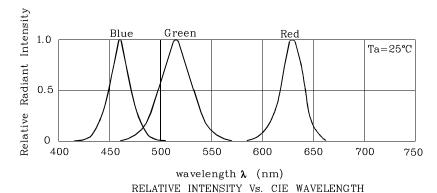
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

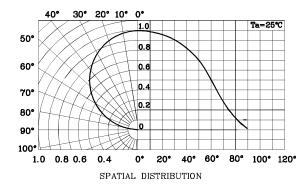


Part Number: XZMECBDDG45S

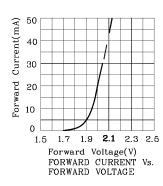
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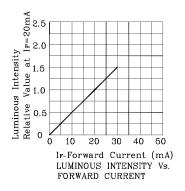


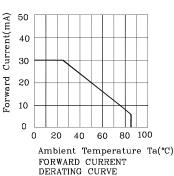


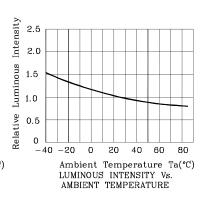


❖ Red

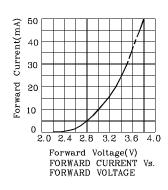


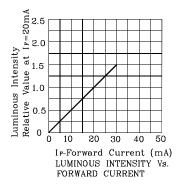


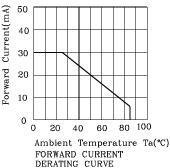


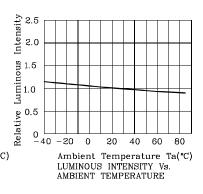


♦ Blue

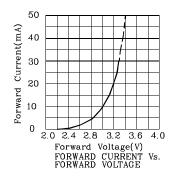


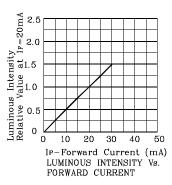


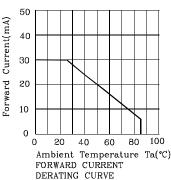


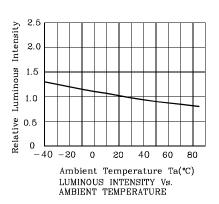


♦ Green





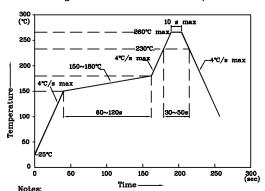




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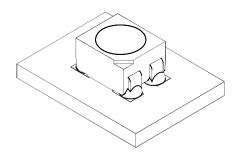
❖ LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

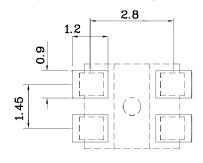


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

❖ The device has a single mounting surface. The device must be mounted according to the specifications.



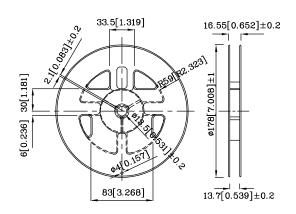
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Tape Specification (Units:mm)

TAPE 4.0±0.1 2.0±0.1 4.0±0.1 0.25±0.1 2.15±0.1 1 3 4 2 3 2

❖ Reel Dimension



Remarks:

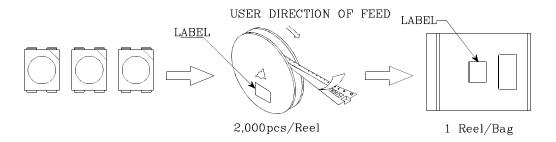
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

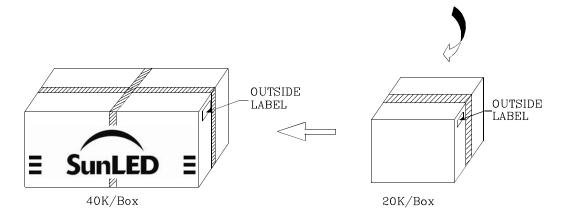
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

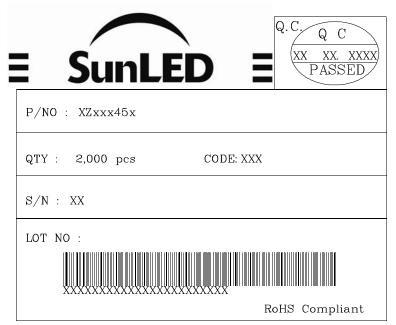
Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS







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